



Developer of Additive Manufacturing Parameter Predictor (AMP²) software and Open Sensor Interface (OSI)

AMP² 2018



Glazing Power = 150W Velocity = 0.4 m/sec



2nd Prize CA prediction (Case 1) 20 µm


Solidification Microstructure Modeling

Our Awards in AM Challenges for Modeling, Scan Path Generation, and Digital Thread Analytics

2022




Phase II Award \$50,000




AMNOW Digital Thread data analytics to discover flaws and trends

Metals Challenge

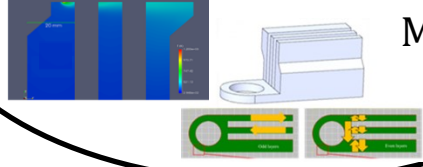
AMP² 2017




\$40,000 2nd Prize



America Makes Part-Scale Process Modeling

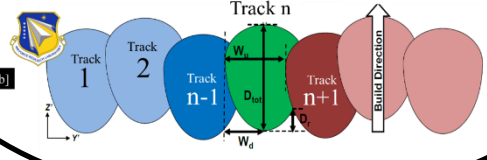


AMP² 2020




3rd Place

Melt Pool Modeling

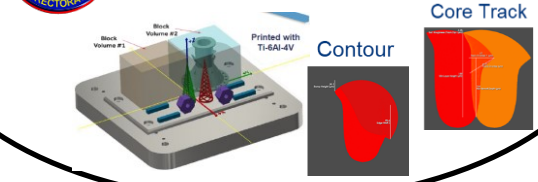


ALSAM AMP² 2021

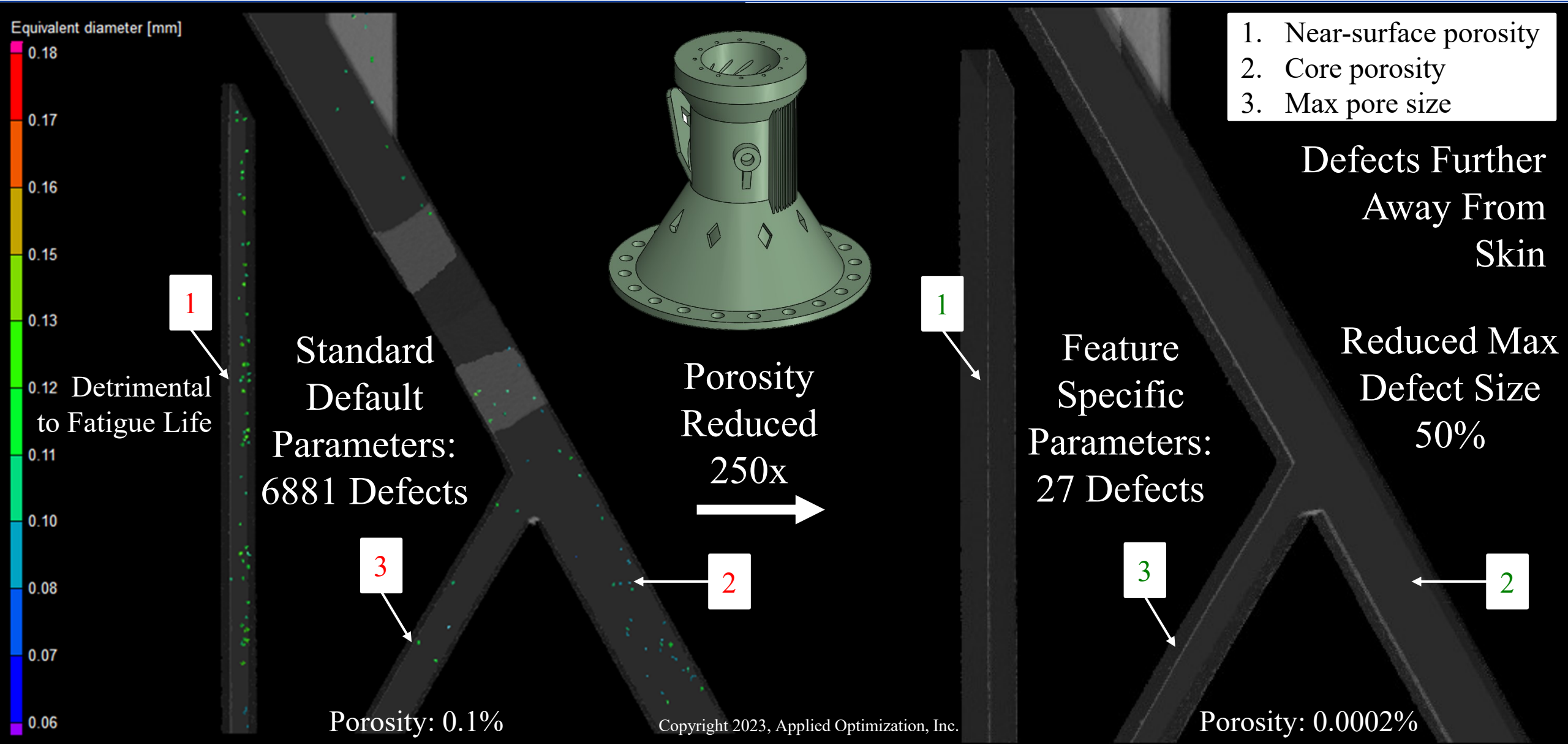


\$11,600 3rd Prize

Scan Path Generation

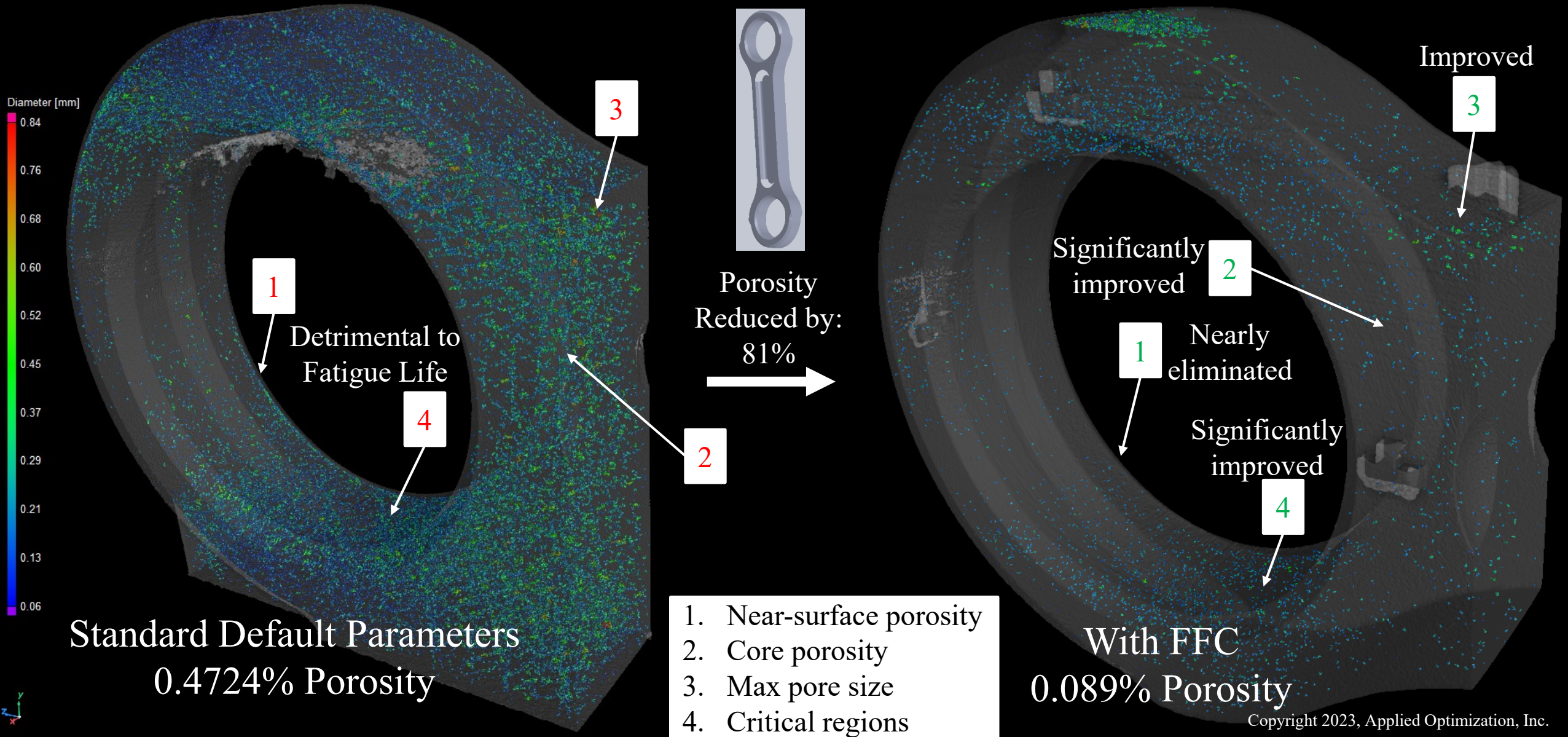


250x Reduction in Defects using Track-by-Track Feature-Specific Parameters (FSP)



Feed-Forward Control (FFC) of Laser Powder Bed Fusion

Layer-by-Layer Process Control (Its methods drew upon the understanding gained using **process simulation**)



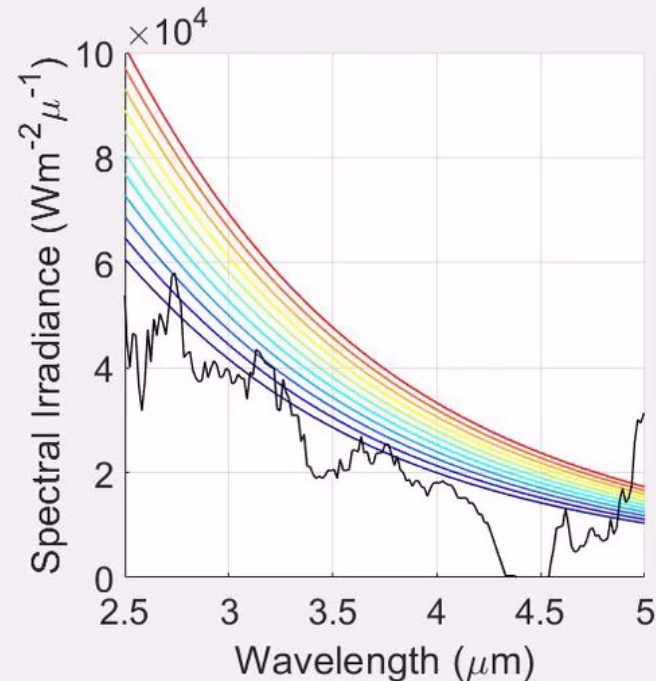
Track-by-Track High-Resolution In-Situ Sensing Data for the Entire Build to Validate FSP predicted by Process Simulations

Melt pool Data (Our 1st Experiment)

MWIR Spectrometer Data (SM32Pro)

1.5 – 5 μm waveband

FOV: 1x4 mm², SNR ~1-3

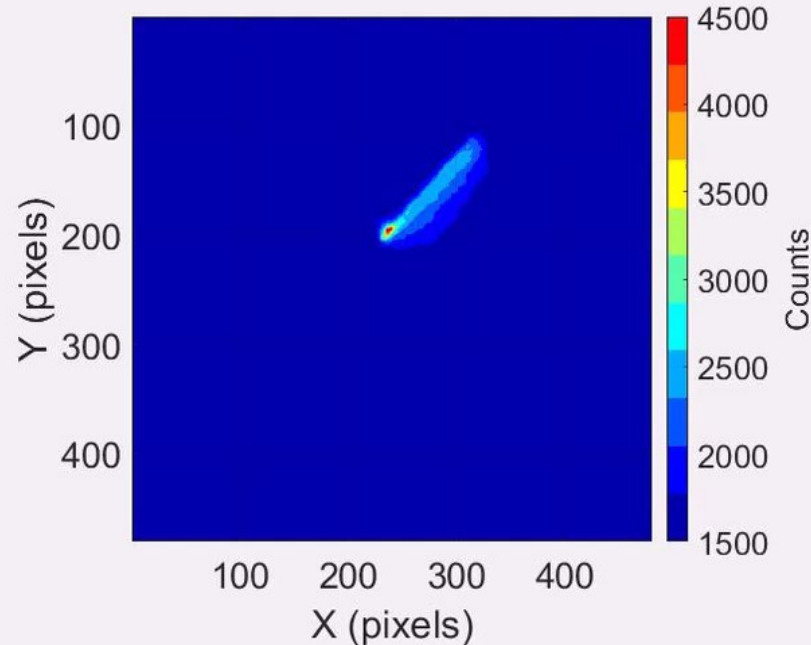


Adjacent to Melt pool

MWIR Thermal Imager Data (FLIR)

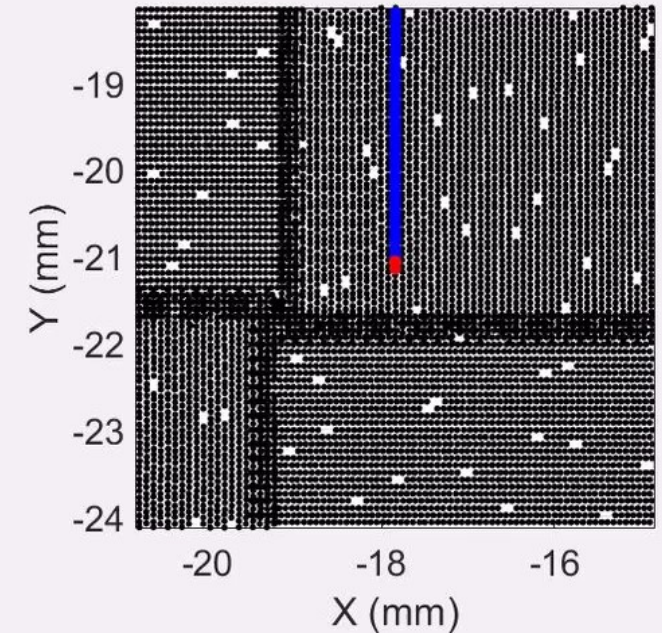
500x500 pixels, 3-5 micron waveband

70 μm resolution, Pixel resolution: 39 μm



Boresight Location

Data is registered with
Scan Path Track Vectors



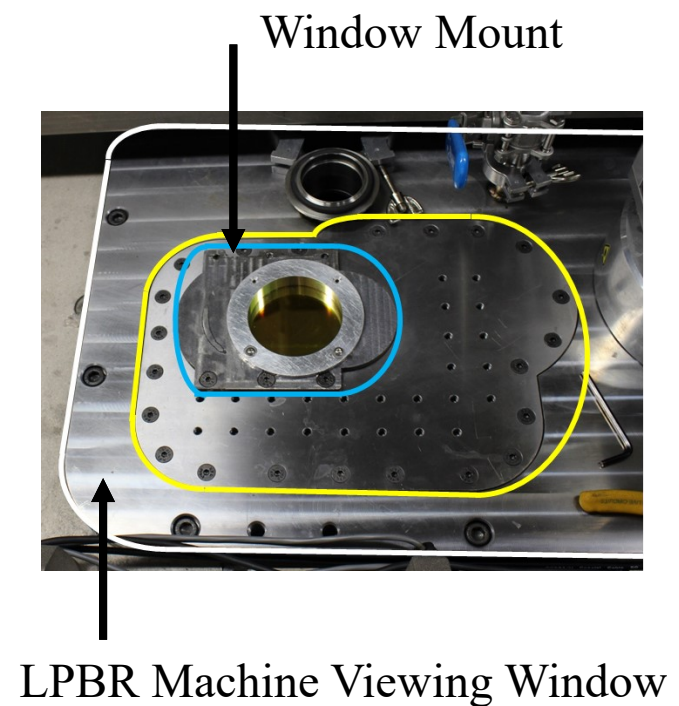
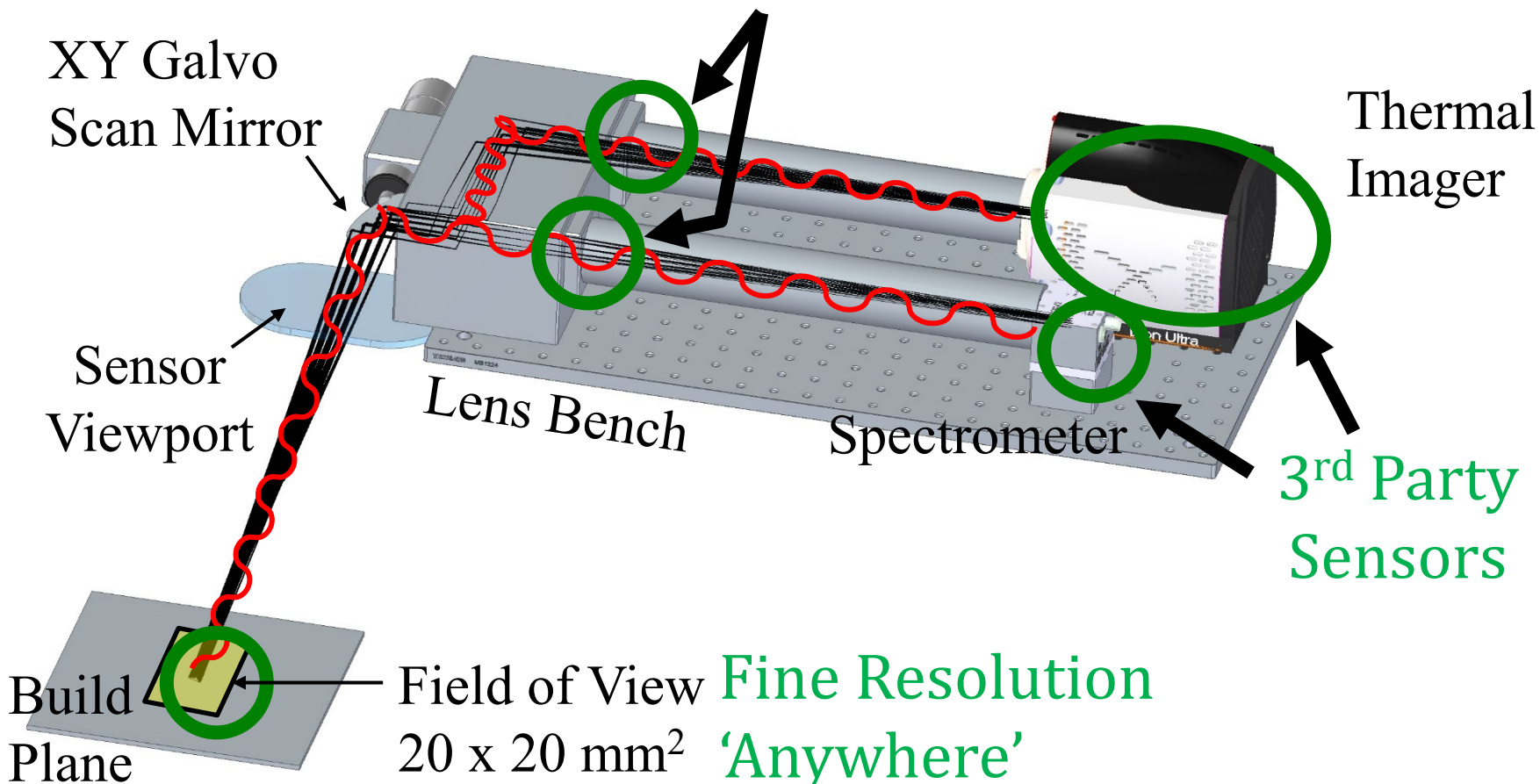
This data was collected in April 2023 for ~400 layers. Such data can be collected anywhere on the build plane.

We had a low SNR (~1 to 3), we are modifying the optics design to significantly increase the SNR

Track-by-Track In-Situ Sensing to:
(1) Validate FSP, and (2) Control the LPBF Process

Challenges: (1) Data management, interoperability and reusability for the cross-correlation data from in-situ sensing and physics-based models, (2) To navigate IP issues for commercial systems

Open Sensor Interface (OSI)



US Patent Pending:
17/202,945



Difficulties to Transition Products

- We do not need it
 - AM part quality is good enough
 - Need improvement for critical parts
 - Who is going to pay for it
 - Need to prove mechanical properties
- Demonstration of maturity metrics for the models
 - Repeatability and reliability
 - Need material and scan path data
- People challenge at customer facilities
 - Consistent availability of a trained person
- CMMC Level 2 compliance
 - High cost + Lack of people



Data Needs and Challenges

For enhancing the value proposition for Additive Manufacturing

- Limited interoperability and reusability of data to report
 - Process simulation results
 - Part-specific predictions
 - Feature specific parameters
 - Cross-correlation with in-situ sensing
 - Schema for a Technology Data Package
 - Evidence of higher TRL
- Fulfilment of IP requirements for proprietary systems, e.g.,
 - Unavailability of scan path
 - Neutral interface for data exchange
 - Reduce work-in-progress costs
- High-temperature material properties data
 - We can generate properties using thermodynamic modeling
 - Experimental data is very limited, particularly for liquid phase
- Insufficient metadata in the historical project records to
 - Validate and mature models